

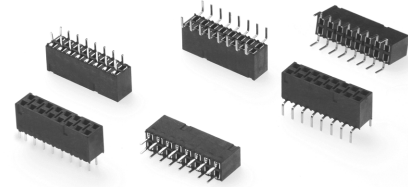
349

Buchsenleiste - RM 2,54 mm - 2-reihig - Bauhöhe 7,3 mm

Female Header - Pitch 2,54 mm - Double Row - Height 7,3 mm

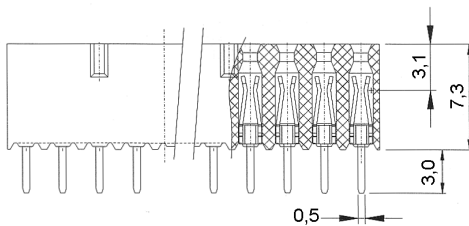
Technische Daten / Technical Data:

Isolierkörper	Thermoplastischer Kunststoff, nach UL94V0
Insulator	Thermoplastic, rated UL94V0
Kontaktmaterial	Kontakt für Vierkantstift \square 0,635 mm, CuZn 30
Contact Material	Contact for Square Pin \square 0,635 mm, CuZn 30
Kontaktfläche	lt. Oberflächenoptionen, über Ni (1,3-2,5 μ m)
Contact Surface	acc. to options (see below), over Ni (1,3-2,5 μ m)
Lötbarkeit	IEC512-12A
Solderability	IEC512-12A
Durchgangswiderstand	≤ 20 mOhm
Contact Resistance	≤ 20 mOhm
Isolationswiderstand	$> 10^9$ Ohm
Insulation Resistance	$> 10^9$ Ohm
Spannungsfestigkeit	1000 V _{DC}
Test Voltage	1000 V _{DC}
Nennspannung	250 V _{AC}
Current Voltage	250 V _{AC}
Nennstrom	3 A
Current Rating	3 A
Temperaturbereich	-40°C...+105°C
Temperature Range	-40°C...+105°C
Verarbeitung	Reflow-Lötverfahren; weitere Informationen in Kapitel T
Processing	Reflow-Soldering, further informations in chapter T

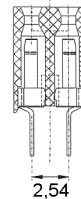


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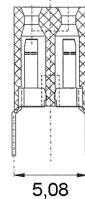
Einsetzbar für Vierkantstift \square 0,635 mm
Accepts square pin \square 0,635 mm



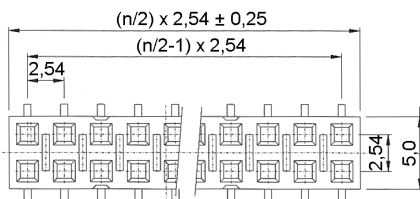
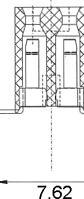
Layout 1



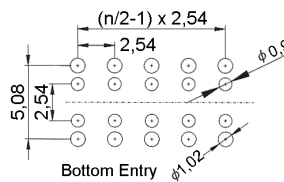
Layout 2



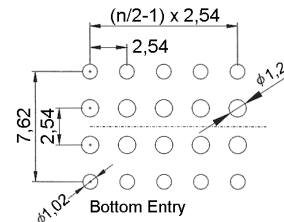
Layout 3



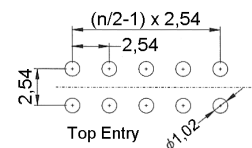
PCB-Layout



PCB-Layout



PCB-Layout



n = Anzahl Kontakte
n = No. of Contacts

Series	Contacts*	Layout*	Plating*
349	04	1	50
	04-80-pol. zweireihig double row	1 = Raster 2,54 mm Dip Spacing 2 = Raster 5,08 mm Dip Spacing 3 = Raster 7,62 mm Dip Spacing	00 = vergoldet gold plated 50 = verzinkt tin plated 60 = sel. Au/Sn duplex plating Au/Sn

(* Bestellbeispiel - Bitte durch Ihre Spezifikationen ersetzen.
* Order example - To be replaced by your specifications.)

Informationen zum Reflow-Lötverfahren

Reflow-Soldering Informations

Reflow-Lötverfahren Reflow-Soldering

Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Lötten im Reflowverfahren verarbeitet werden (Maximalwerte):

Profil Eigenschaft	Bleifreies Lötten
Durchschnitts-Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3 °C / Sek. Max.
Vorheizen - Temperatur Min ($T_{s_{min}}$) - Temperatur Max ($T_{s_{max}}$) - Zeit ($t_{s_{min}}$ auf $t_{s_{max}}$)	150°C 200°C 60-180 Sekunden
Verbleiben oberhalb: - Temperatur (T_L) - Zeit (t_L)	217°C 60-150 Sekunden
Peak/Klassifizierung Temperatur (T_p)	260°C +/- 5°C
Zeit innerhalb von 5°C um die Peak-Temperatur (t_p)	20-40 Sekunden
Ramp-Down Rate	6°C / Sekunde max.
Zeit von 25°C bis zur Peak-Temperatur	8 Minuten max.

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Items should be soldered according to IPC/JEDEC J-STD-020C temperature-profile for leadfree reflow-soldering (maximum values):

Profile Feature	PB-Free assembly
Average Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3 °C / second max.
Preheat - Temperature Min ($T_{s_{min}}$) - Temperature Max ($T_{s_{max}}$) - Time ($t_{s_{min}}$ to $t_{s_{max}}$)	150°C 200°C 60-180 seconds
Time maintained above: - Temperature (T_L) - Time (t_L)	217°C 60-150 seconds
Peak/Classification Temperature (T_p)	260°C +/- 5°C
Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-Down Rate	6°C / second max.
Time 25°C to Peak Temperature	8 minutes max.

Empfohlenes Reflow-Lötprofil:

Recommended Reflow-Soldering profile:



T